



2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/077,452

Filed: February 14, 2002

For: METHOD AND APPARATUS FOR
TRANSFER MOLDING ENCAPSULATION
OF A SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK

Examiner: Unknown

Group Art Unit: 2814

Attorney Docket No.: 3061.6US (96-893.5)

#3
Richard Wensel
5-23-02

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

May 13, 2002
Date of Deposit

[Signature]
Signature of registered practitioner or other person
having reasonable basis to expect mailing to occur
on date of deposit shown pursuant to 37 C.F.R. §
1.8(a)(1)(ii)

Deidra Pfeil
Typed/printed name of person whose signature is
contained above

PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

RECEIVED
MAY 17 2002
TC 2800 MAIL ROOM